

**Description**

The SX70P03NF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = -30V$   $I_D = -78A$

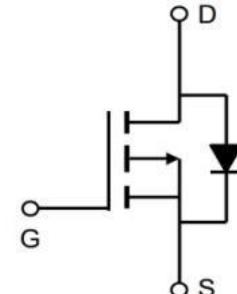
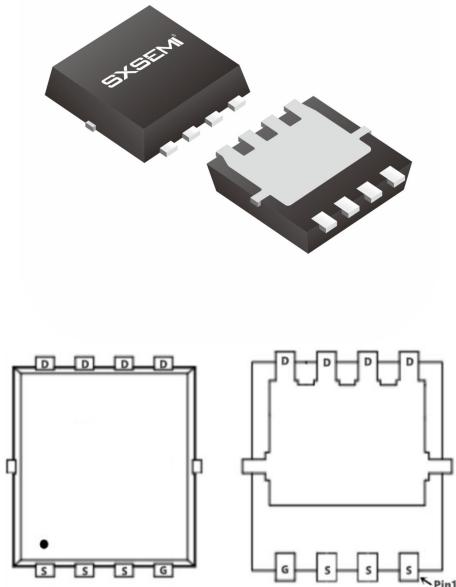
$R_{DS(ON)} < 7.5m\Omega$  @  $V_{GS} = -10V$

**Application**

Lithium battery protection

Wireless impact

Mobile phone fast charging

**PDFN5\*6-8L****Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	$\pm 20$	V
I <sub>D@TC=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V1	-78	A
I <sub>D@TC=100°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V1	-57	A
I <sub>DM</sub>	Pulsed Drain Current2	-200	A
E <sub>AS</sub>	Single Pulse Avalanche Energy3	125	mJ
I <sub>AS</sub>	Avalanche Current	-40	A
P <sub>D@TC=25°C</sub>	Total Power Dissipation4	69	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient 1	25	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case1	1.6	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-30	-34	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.0232	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_D=-20\text{A}$	---	5.2	7.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-15\text{A}$	---	8.0	11	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D =-250\mu\text{A}$	-1.2	-1.4	-2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	4.6	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_D=-30\text{A}$	---	30	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	9.8	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ $I_D=-20\text{A}$	---	35	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	9.9	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	10.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_g=3.0\Omega$ $I_D=-20\text{A}$	---	10.8	---	ns
$T_r$	Rise Time		---	13.2	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	73	---	
$T_f$	Fall Time		---	35	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3520	---	pF
$C_{\text{oss}}$	Output Capacitance		---	465	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	370	---	
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-70	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	-130	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.3	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=-20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	25	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	10	---	nC

**Note :**

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 4、EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}= -24\text{V}$ ,  $V_{\text{G}}= -10\text{V}$ ,  $R_g=7\Omega$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}= -40\text{A}$
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

## Typical Characteristics

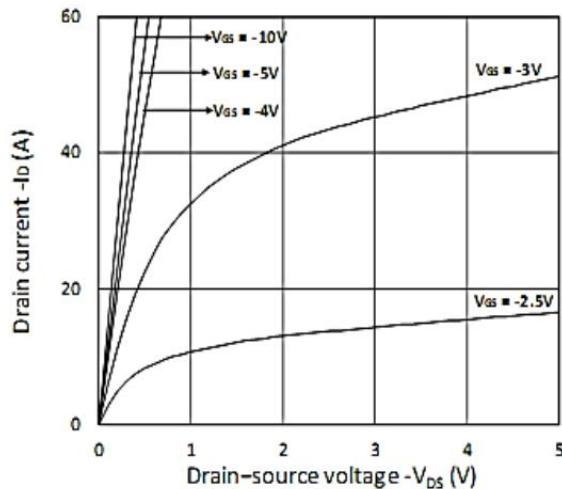


Figure 1. Output Characteristics

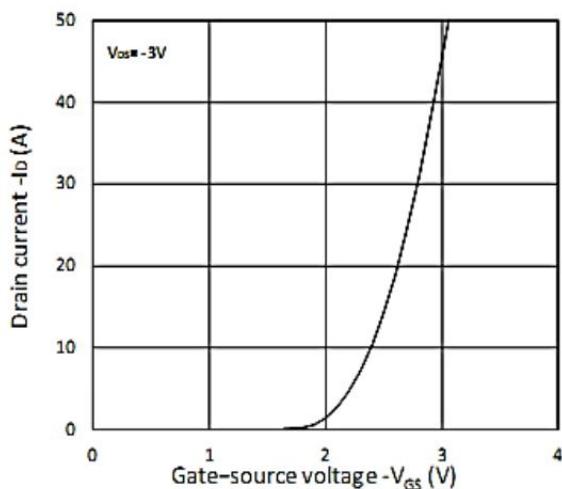


Figure 2. Transfer Characteristics

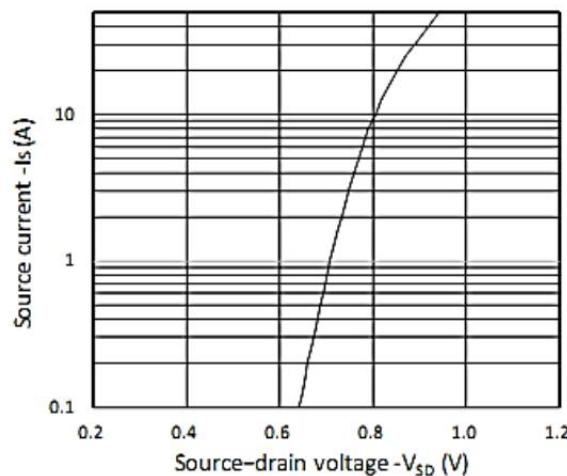
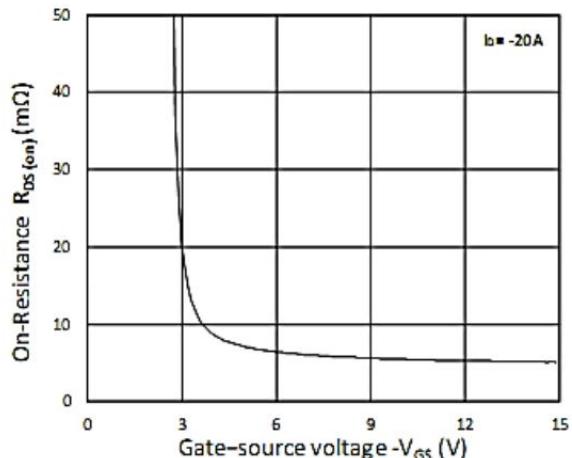
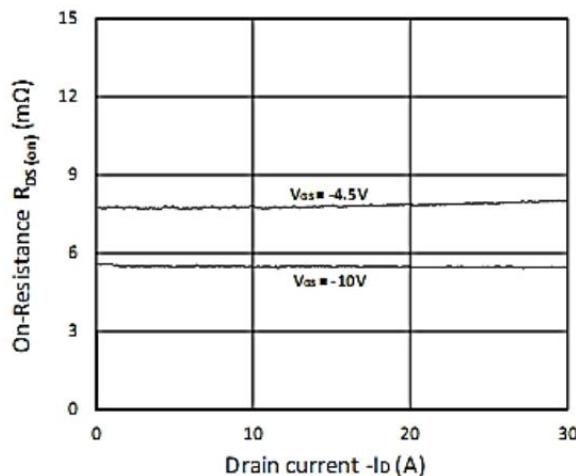
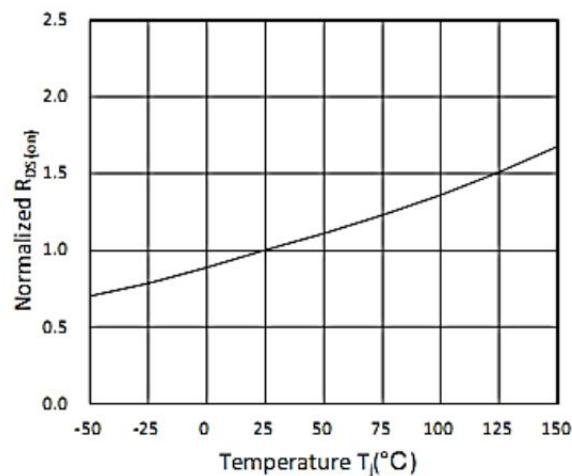


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

## Typical Characteristics

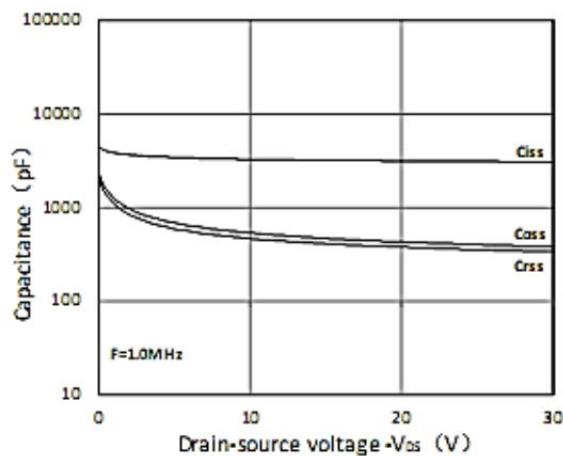


Figure 7. Capacitance Characteristics

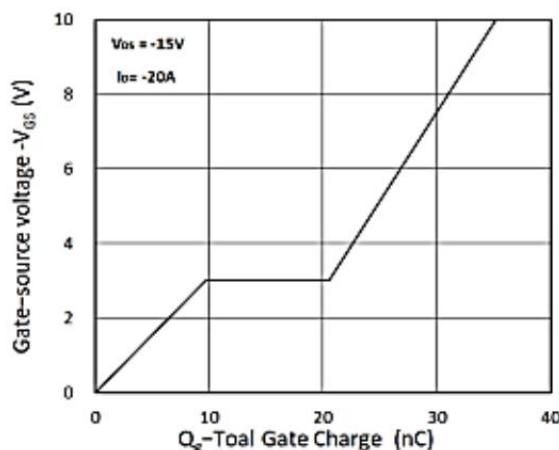


Figure 8. Gate Charge Characteristics

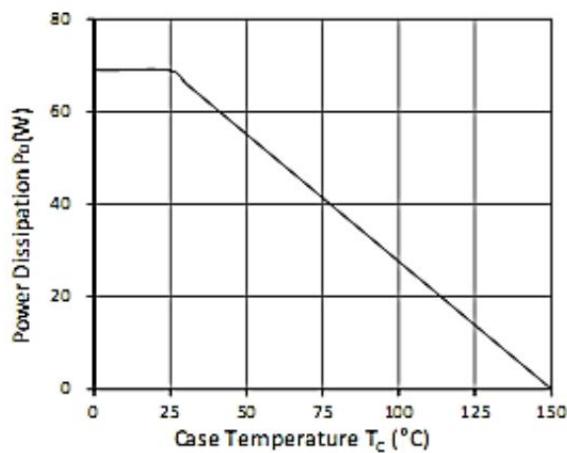


Figure 9. Power Dissipation

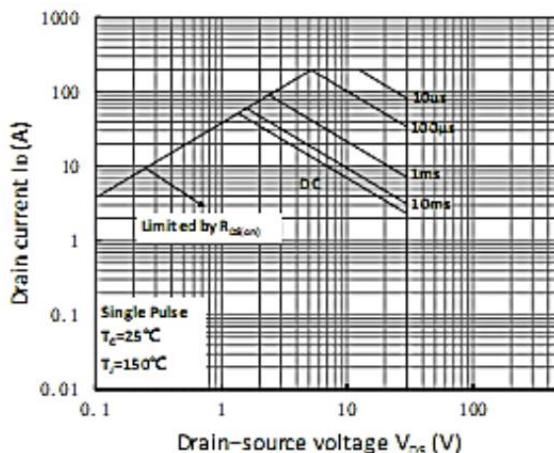


Figure 10. Safe Operating Area

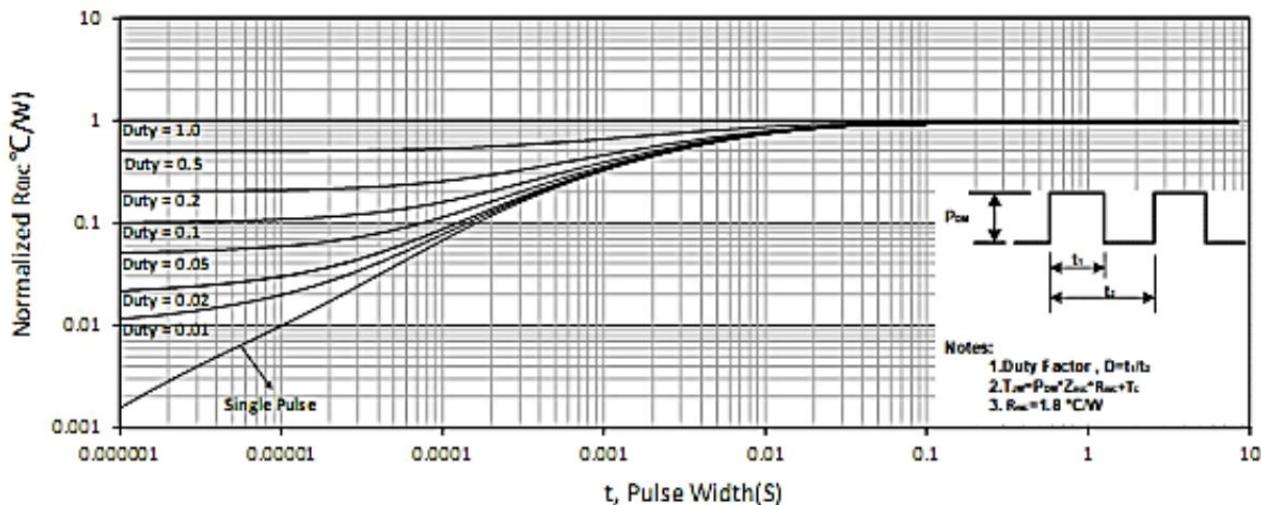
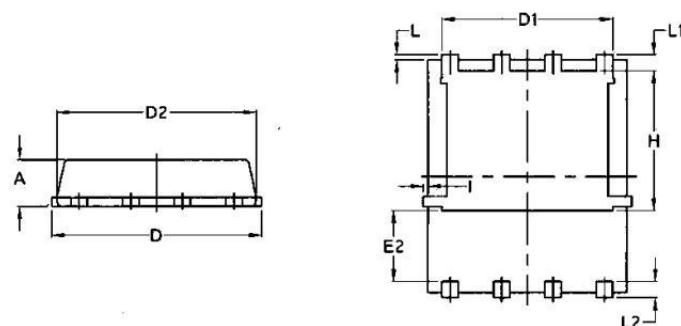
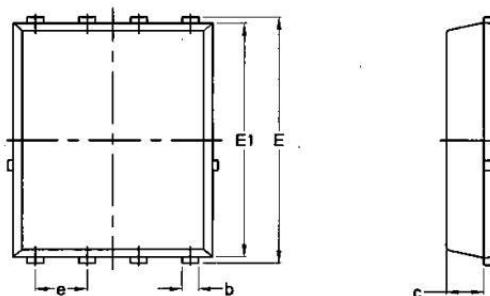


Figure 11. Normalized Maximum Transient Thermal Impedance

## Package Mechanical Data- PDFN5\*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN5*6-8L		5000